High Performance BGA Cooling Solutions with maxiGRIP™ Attachment

ATS PART # ATS-53325G-C1-R0

Features & Benefits

- High aspect ratio, straight fin heat sinks that are ideal for compact PCB environments
- maxiGRIP™ attachment applies steady, even pressure to the component and does not require holes in the PCB
- Designed specifically for BGAs and other surface mount packages
- Meets Telcordia GR-63-Core Office Vibration, ETSI 300 019 Transportation Vibration, and MIL-STD-810 Shock testing and Unpackaged Drop Testing standards
- Comes preassembled with high performance, phase change, thermal interface material
- "Keep-Out" Requirements: An "Un-Populated" boarder zone of 5 mm around the component is necessary to facilitate the Installation/ Removal of the maxiGRIP™. Please refer to the maxiGRIP™ Keep-Out Guidelines and maxiGRIP™ Installation/Removal Instructions for further details

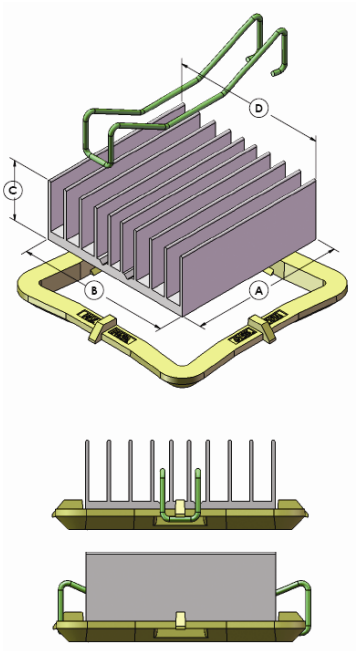


Image above is for illustration purposes only.

Thermal Performance

AIR VELOCITY		THERMAL RESISTANCE	
FT/MIN	M/S	°C/W (UNDUCTED FLOW)	°C/W (DUCTED FLOW)
200	1.0	5.9	3.2
300	1.5	4.4	
400	2.0	3.7	
500	2.5	3.3	
600	3.0	3.0	
700	3.5	2.8	
800	4.0	2.6	

Product Details

DIMENSION A	DIMENSION B	DIMENSION C	DIMENSION D	INTERFACE MATERIAL	FINISH
32.5 mm	32.5 mm	12.5 mm	32.5 mm	CHOMERICS T766	BLUE ANODIZED

NOTES:

1) DIMENSIONS ARE MEASURED IN MILLIMETERS
2) DIMENSIONS A & B REFER TO COMPONENT SIZE
3) DIMENSION C = THE HEIGHT OF THE HEAT SINK SHOWN ABOVE AND DOES NOT INCLUDE THE HEIGHT OF THE ATTACHMENT METHOD
4) ATS RESERVES THE RIGHT TO UPDATE OR CHANGE IT PRODUCTS WITHOUT NOTICE
5) CONTACT ATS TO LEARN ABOUT CUSTOM OPTIONS AVAILABLE

ATS ADVANCED THERMAL SOLUTIONS, INC.
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For more information, to find a distributor or to place an order, visit www.qats.com or call: 781.769.2800 (North America); +31 (0) 3569 84715 (Europe).